

### Burn-in & Test Socket Workshop

IEEE

March 3-6, 2002 Hilton Phoenix East/Mesa Hotel Mesa, Arizona



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Test Technology Technical Council



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#### **Technical Program**

Session 1 Monday 3/04/02 8:30AM

**Socket Design Investigations** 

"Effect Of High Temperature Heating On Music Wire Spring Performance"

Jiachun (Frank) Zhou - Kulicke & Soffa Interconnect, Inc. January Kister - Kulicke & Soffa Interconnect, Inc. Alberto M. Campos - Kulicke & Soffa Interconnect, Inc.

"Low Cost Burn-in Socket Design For Area Array Package (BGA)" Ichiro Fujishiro - Yamaichi Electronics, USA Inc.

"Force and Resistance Probing Automation for Contactors"

Valts Treibergs - Everett Charles Technologies

Jason Mroczkowski - Everett Charles Technologies



# Effect of High Temperature Heating on Music Wire Spring Performance

Jiachun Zhou (Frank), presenter January Kister Alberto M. Campos

> Kulicke & Soffa 3387 Investment Blod Hayward, CA 94545 Ph: (510)782-2656





#### Introduction

Material Name and Specification	Max Service Temp.		
Material Name and Specification	F	С	
Music Wire, ASTMA228	250	121	
Austenitic Stainless Steel AISI 302	600	316	
Beryllium Copper, ASTM B197	400	204	

Data from reference.

May not be suitable for small spring with < 0.1mm diameter wire.



#### **Objectives**

Investigate the effects of high temperature heating on spring performance.

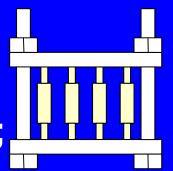
Verify suitable temperature range of music wire spring application (<0.1mm wire diameter).

Analyze the root-cause of spring failure in high temperature environment.



#### **Test Methods**

Compressed spring in parallel plates;



Heating compressed springs in high temperature oven for a period of time;

Force-deflection measurements (at room temperature) after taking the springs out of oven.



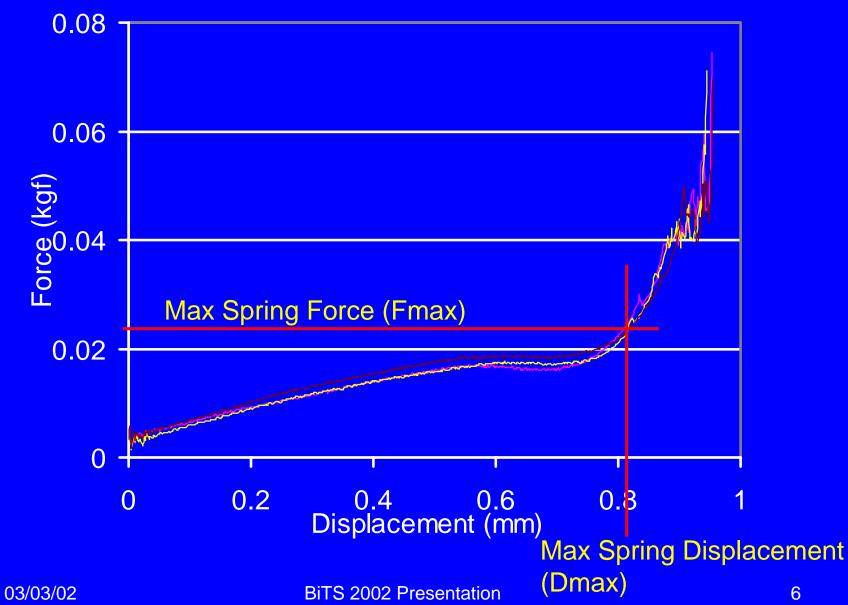
#### **Spring Sample**

Sample	OD (mm)	Free Length (mm)	Wire Diameter (mm)
<b>S1</b>	0.49	1.70	0.06
S2	0.65	3.80	80.0
<b>S</b> 3	0.38	5.20	0.065

Material: Music wire, carbon steel (~0.8% C)

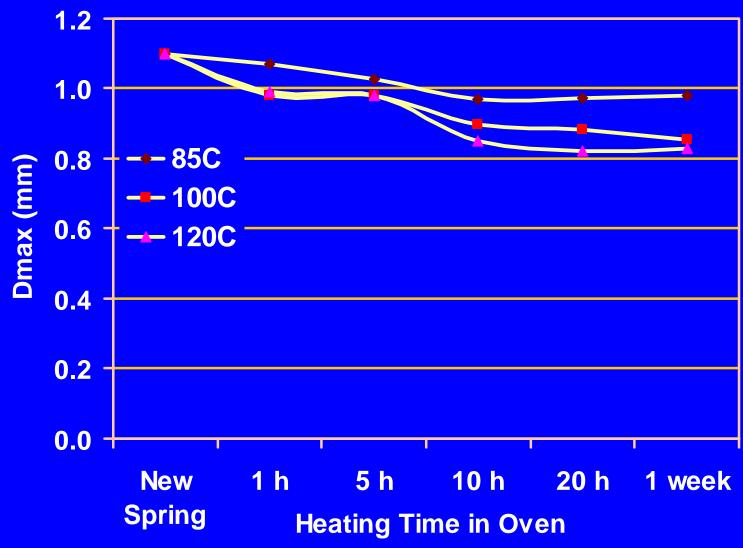


#### **Criteria of Performance Evaluation**





## Max Displacement vs H.T. vs Temp. (S1)





#### Max Force vs. H.T. vs Temp. (S1)





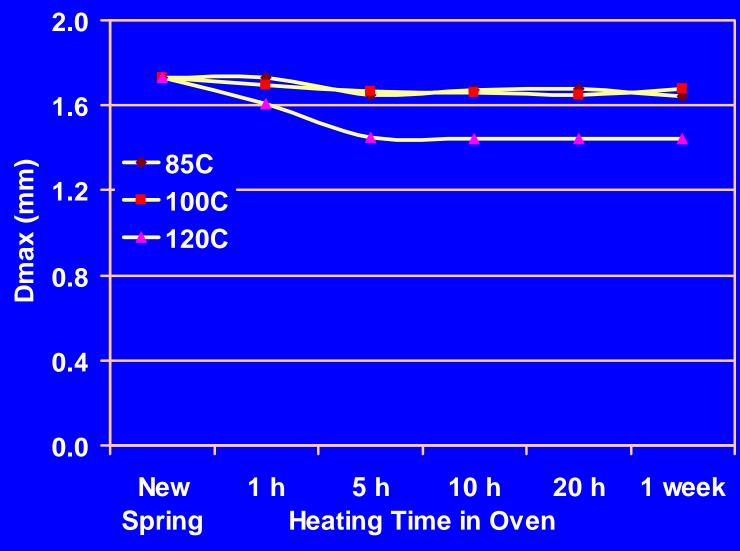
#### Comparison: New Spring vs after 120°C x 1 week (S1)

0.08 mm

**Spring** After 120Cx Iweek after 120°C x 1 week New Spring-1.75 mm

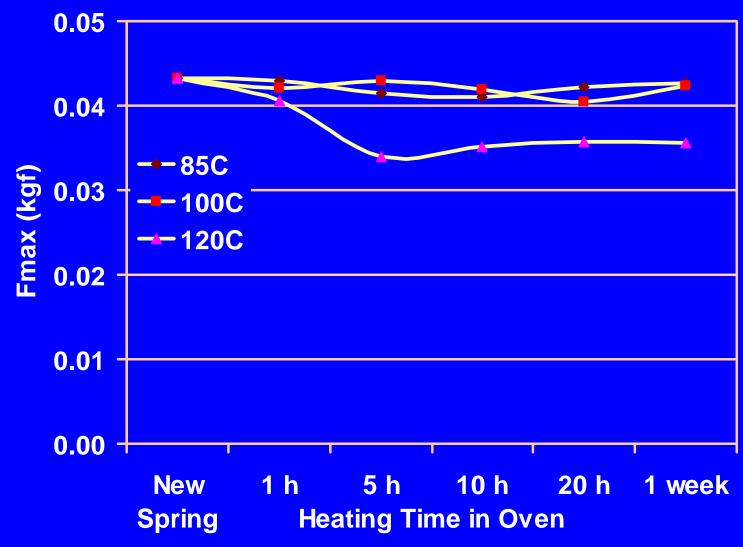


## Max Displacement vs H.T. vs Temp. (S2)





#### Max Force vs. H.T. vs Temp. (S2)

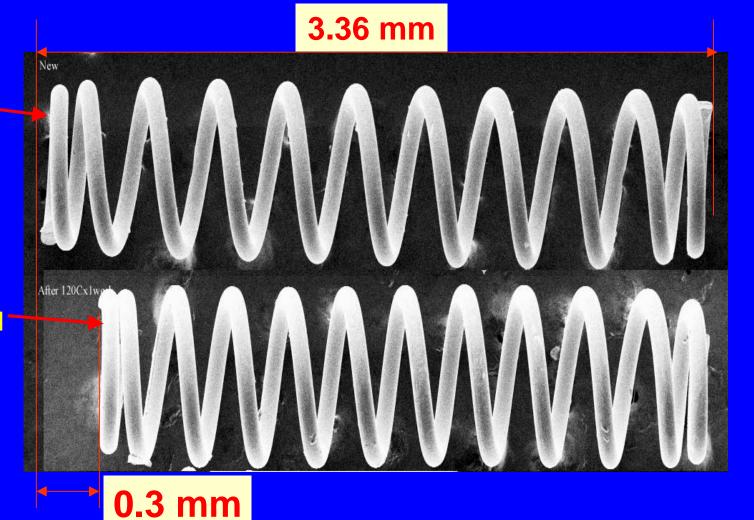




## Comparison: New Spring vs after 120°C x 1 week (S2)

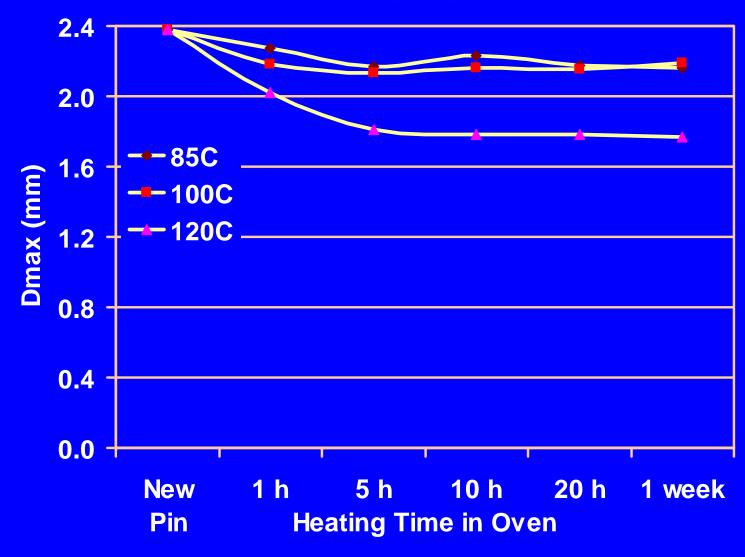
New Spring

Spring after 120°C x 1 week



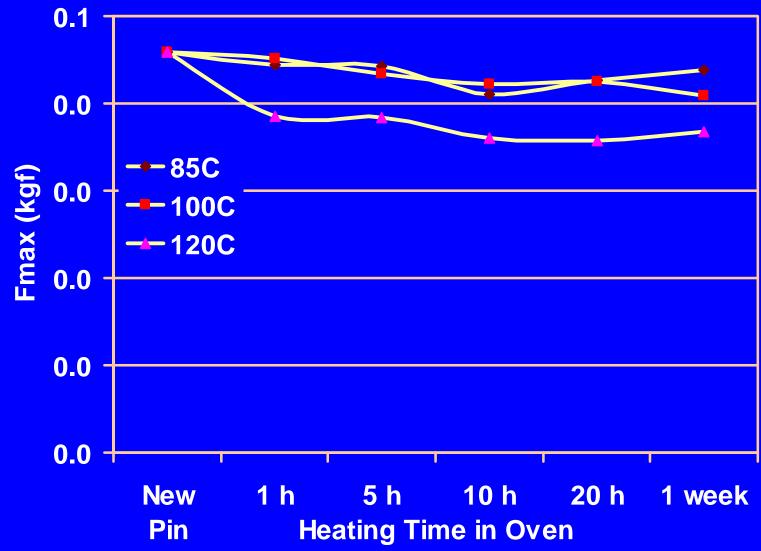


## Max Displacement vs H.T. vs Temp. (S3)



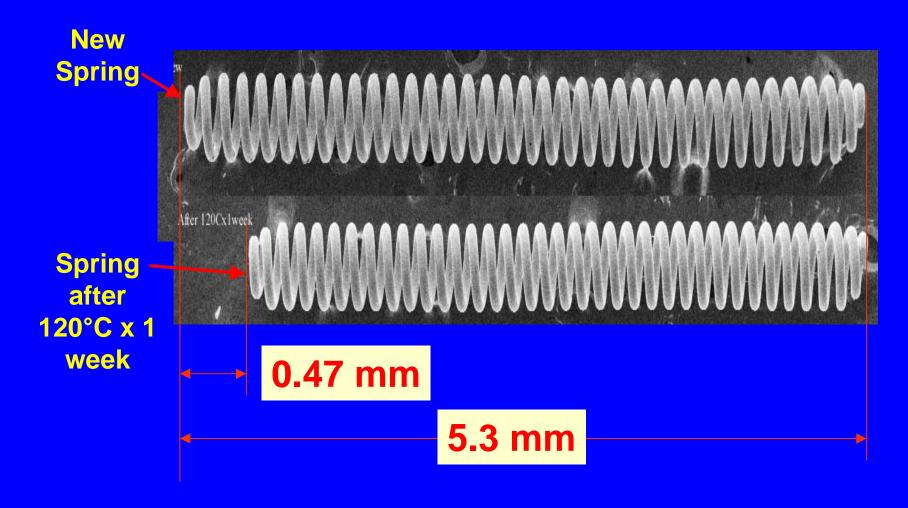


#### Max Force vs. H.T. vs Temp. (S3)





## Comparison: New Spring vs after 120°C x 1 week (S3)





#### Summary - 1

<100°C heating has little effects on small music wire spring (<0.1mm wire diameter).

>120°C heating, maximum displacement of spring decrease significantly after about 20 hours. Less than 20 hours, the spring can maintain normal performance.



#### Summary – 2

Permanent deformation (length shortage) of spring during heating causes the reduction of maximum displacement of spring.

The length shortage due to heating at 120°C for one week ranges 5~10% for music wire spring. But spring keeps good elasticity and displacement range with linear F-D relation even though spring is short.



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## Low cost Burn-in Socket Design for Area Array Package (BGA)

2002 Burn-in and Test Socket Workshop

March 3 - 6, 2002







#### Contents

- Market Trend.
- Considerations in the Development of Low Cost Burn-In Socket for BGA.
- Appearance of Low Cost Burn-In Socket for BGA.
- Socket Components Comparison.
- Operation of Low Cost BGA Socket.
- Features of Low Cost BGA Socket.
- Conclusion



Source: Semiconductor Assembly Council

#### 1. Market Trend Worldwide IC Shipments by Package Family

	2000	2001	2002	2003	2004	2005	CAGR (%)
Package Units (M)							
DIP	10,098	7,492	7,426	7,192	7,286	7,459	-5.9
so	53,090	49,010	55,428	60,139	67,549	76,911	7.7
СС	2,422	2,150	2,188	2,215	2,331	2,477	0.4
QFP	9,078	8,355	9,399	9,848	11,141	12,828	7.2
PGA	286	261	307	351	383	441	9.1
BGA	2,418	2,660	3,456	4,029	4,871	5,748	18.9
CSP	2,366	3,417	5,295	7,324	9,891	12,168	38.8
DCA	6,755	6,378	7,483	8,154	9,354	10,757	9.8
Total	86,513	79,725	90,983	99,253	112,806	128,789	8.3%



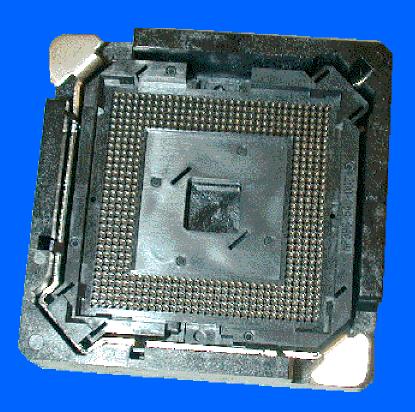
## 2. Considerations in the Development of Low Cost Burn-In Socket for BGA

- Lower Cost with Reduced Component Count.
- Keep High Reliability with Existing Tweezers Type Contact.
- Smaller Size for High Density Assembly.
- Lower Height for Better Wind Flow.
- Easy Matching with Existing Loader/Un-loader.



## 3. Appearance of Low Cost Burn-In Socket for BGA

Low Cost Socket

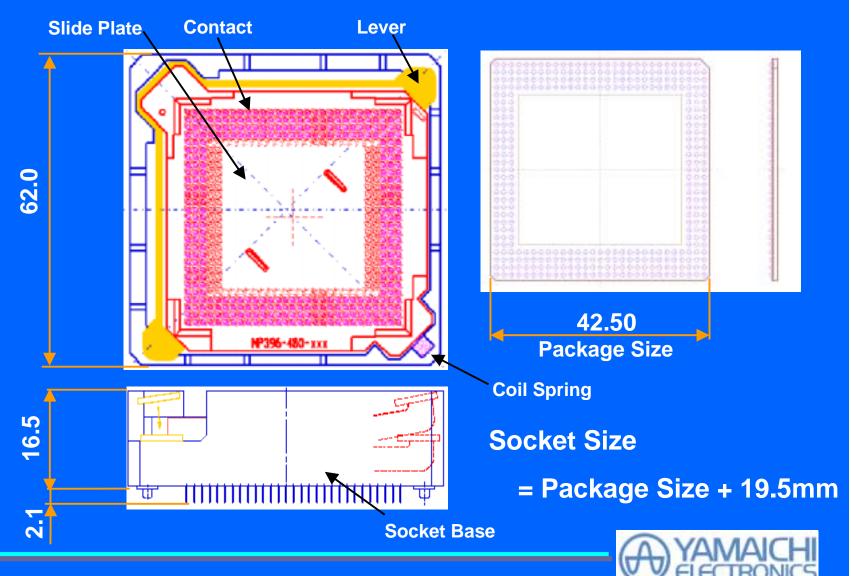


**Existing Socket** 



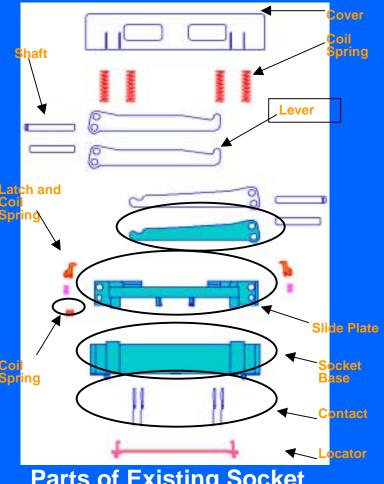


#### 3. Appearance of Low Cost Burn-In Socket for BGA



#### 4. Socket Components Comparison

		New Socket	<b>Existing Socket</b>
1	Socket Base	1	1
2	Slide Plate	1	1
3	Contact	500	500
4	Lever A	1	1
5	Coil Spring A	1	1
6	Locator	none	1
7	Latch	none	2
8	Coil Spring B	none	2
9	Cover	none	1
10	Lever B	none	1
11	Lever C	none	1
12	Lever D	none	1
13	Coil Spring C	none	4
14	Shaft A	none	2
15	Shaft B	none	2
16	Retaining Ring	none	2
	Total	504	523
	Total (w/o Contact)	4	23

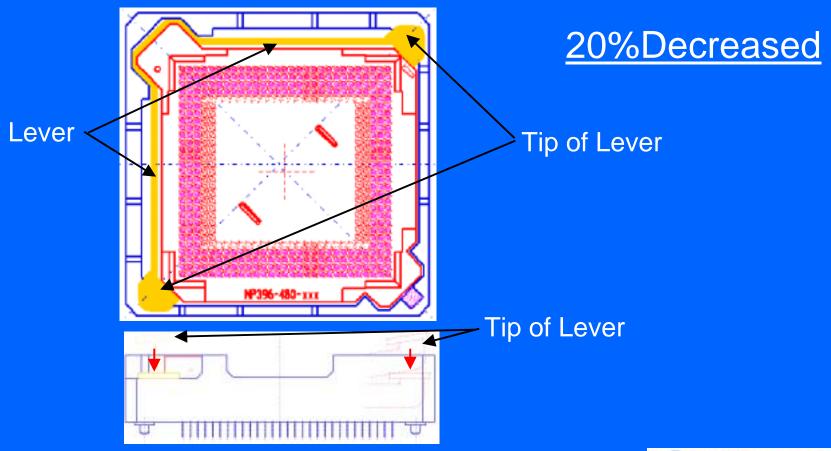




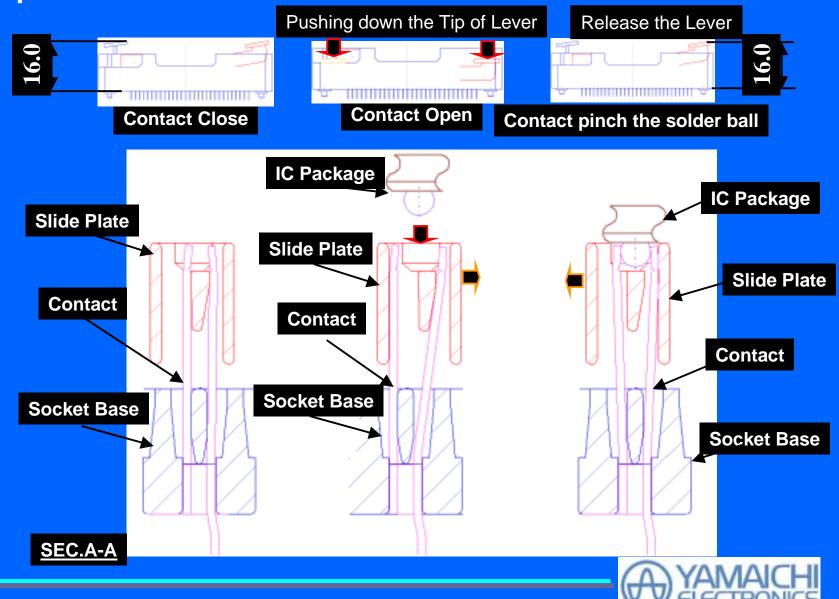


## 5. Operation of Low Cost BGA Socket Lower Operation Force

(Existing Socket = 4.0Kg)



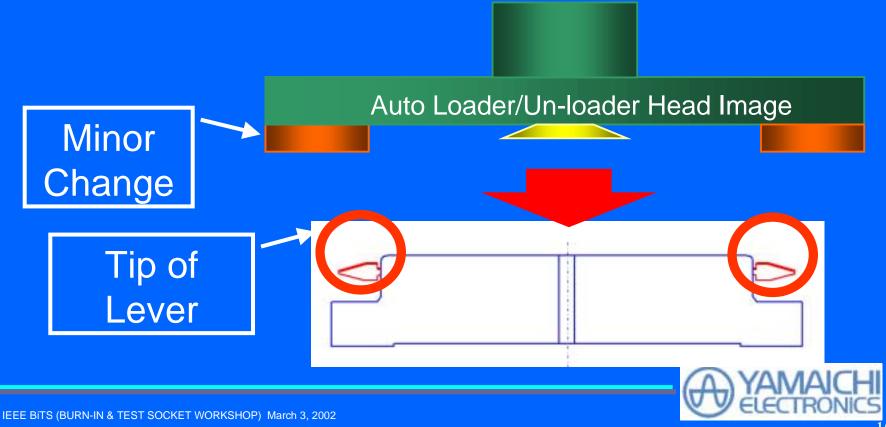
#### 5. Operation of Low Cost BGA Socket



#### 5. Operation of Low Cost BGA Socket

Simplified Actuation Mechanism

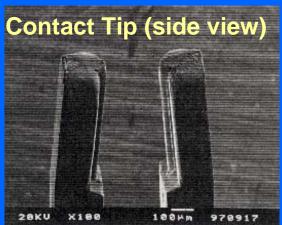
Low cost socket requires a minor change of auto loader/un-loader head

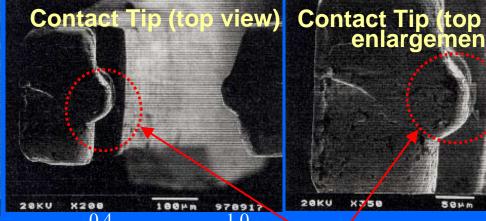


#### 6. Features of Low Cost BGA Socket

#### High Reliability

Utilize previous high reliable contact



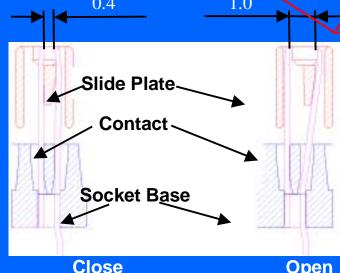




**Each Contacts are** divided by socket base and slide plate.



No short circuit **Precision contact position** No damage to contact



**Applicable Solder** ball diameter

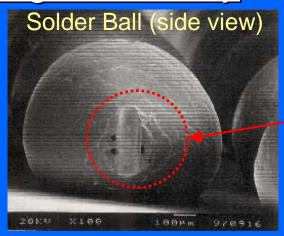
**Contact Point** 

=0.75mm

Open



## 6. Features of Low Cost BGA Socket High Reliability



Solder Ball (top view)

Solder Ball (top view) enlargement

**Contact Mark** 

Small contact mark

No contact mark at the top of solder ball

No sticking problem \_\_\_\_



#### 6. Features of Low Cost BGA Socket

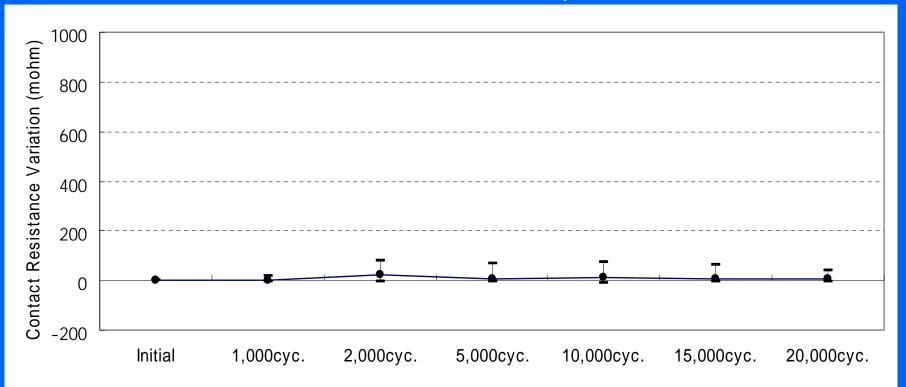
High Reliability

Cycle test (room temperature)

Contact resistance variation

N=2 sockets, 160points (80points/socket)

Data is for loop resistance



Initial = 24.0mohm



#### 6. Features of Low Cost BGA Socket

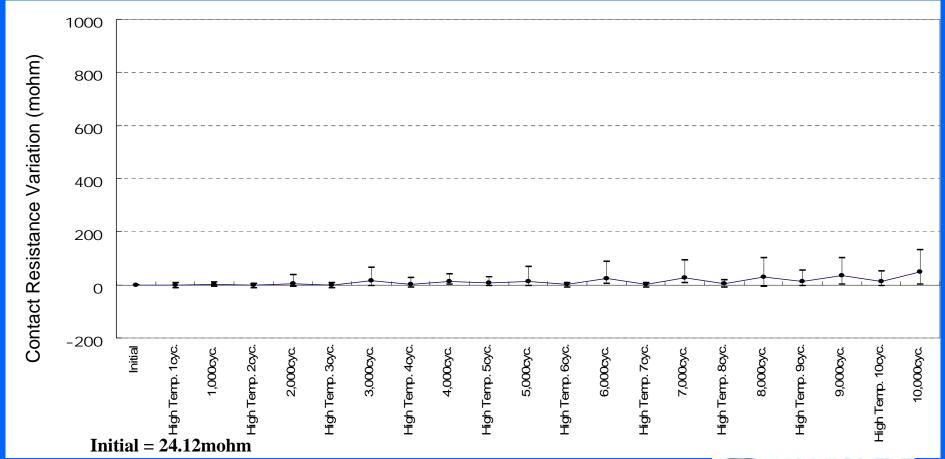
**High Reliability** 

Cycle test (high temperature, 125 degree C / 48h)

Contact resistance variation

N=2 sockets, 160points (80points/socket)

Data is for loop resistance



## 6. Features of Low Cost BGA Socket High Density

Reduced Socket Body Size

Low Cost: 62mm sq.

Existing: 74mm sq.

-12mm

Reduced Socket Area

Low Cost : 3,844mm<sup>2</sup>

Existing: 5,476mm<sup>2</sup>

-1632mm<sup>2</sup>

**30%DOWN** 

Reduced Socket Weight

Low Cost: 46g

Existing: 75g

-29g

Easy handling with light weight



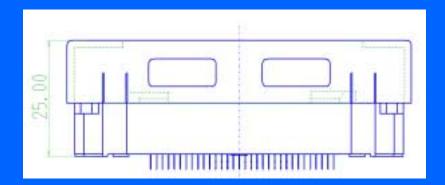
# 6. Features of Low Cost BGA Socket Better Air Flow

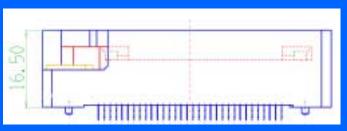
Reduced Socket Height

Low Cost: 16.5mm

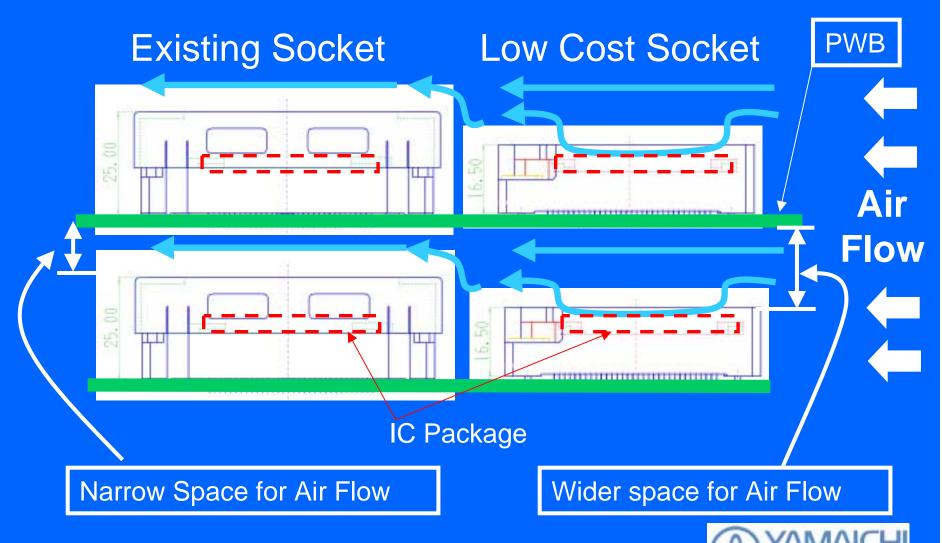
Existing: 25mm

8.5mm





## 6. Features of Low Cost BGA Socket Better Air Flow



#### 7. Conclusion

Development of low cost BGA socket
Reduced Component Count
Cover-less
Shaft-less
High reliability
Utilize previous high reliable contact
High Density and light weight - Smaller
size

Better Air Flow - Lower height

	Existing Socket	New Socket	Difference
Socket Size	74.0mm	62.0mm	12.0mm 16" off
Socket Height	25.0mm	16.5mm	8.5mm 34" off
Socket Area	5,476mm <sup>2</sup>	3,844mm <sup>2</sup>	1,632mm <sup>2</sup> 30 <sub>"</sub> off
Socket Weight	75g	46g	29g 38% off
Component Count (W/O Contact)	23 parts	4 parts	19 parts 82% off
Operation Force	4.0Kg	3.2Kg	0.8Kg 20% off
Loader/Un-Loader Interface	on Cover	on Lever	Coverless



## Force and Resistance Probing Automation for Contactors

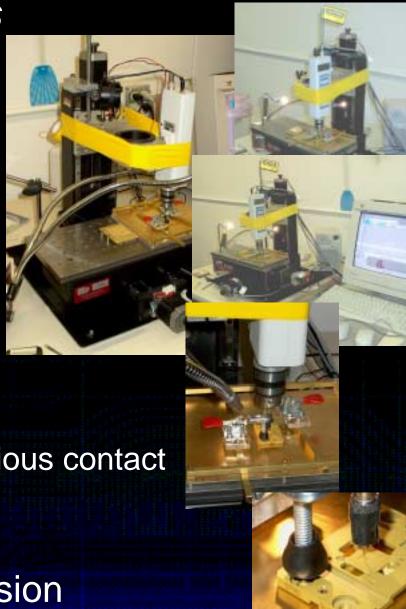
Jason Mroczkowski, Valts Treibergs Everett Charles Technologies March, 2002





**Presentation Topics** 

- STG's Need
- Our Goal
- The Problem
- Our Solution
  - Hardware
  - > Software
  - Probe considerations
- Some Data
  - FReD plots, etc. of various contact technologies
- The Future
- Summary and Conclusion



#### **Our Need**

- ECT-STG needed to automate force and resistance measurements for new contactor technology qualification and production validation
  - Precise force and resistance measurements are very tedious and time consuming
  - Measurement sample sizes tend to be too small statistically significant data sometimes was missed
  - ➤ The 'human element' in data taking sometimes ended in biased or unreliable results
  - Manual testing was not practical for production inspection or for rapid field failure analysis



#### Our Goal

- A programmable X-Y robot with mΩ resistance and gram force sensors with full data acquisition capability
- A unit 'off the shelf' was found Tricor Systems 921 X-Y DFR system

NO PROBLEM!!!





- **921 DFR** X-Y robot DFR system cost: \$49,775.00
- Our allocated budget:



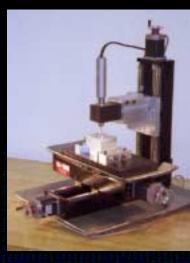
## The Solution

- Build it yourself!!!
- Hmmmm where to start...
- SCROUNGE, SCROUNGE, SCROUNGE

# Existing equipment:











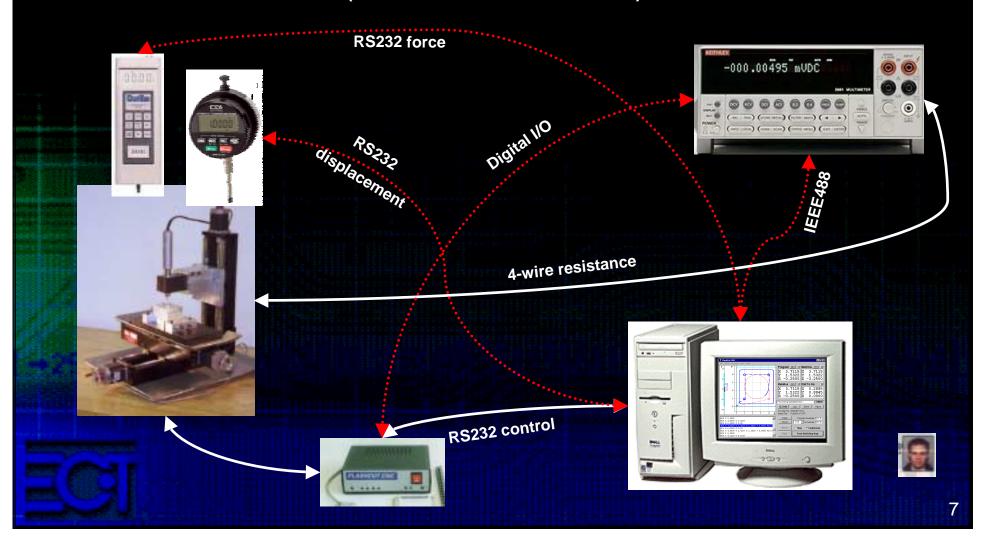






## The Solution (Hardware)

■ The Force Resistance and Displacement System (FReD - for short)

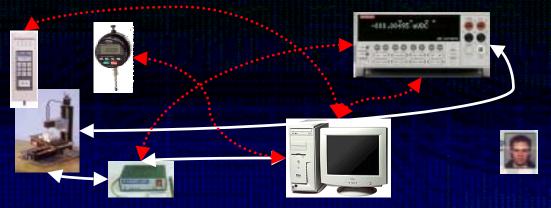


## The Solution (Hardware)

- FReD's missing BiTS:
  - ➤ Indicator serial cable: new \$72
  - ➤ Force gage serial cable: new connector \$3, stolen mouse cable \$0
  - ➤ Additional serial port card on PC: \$26
  - Digital I/O wiring: another stolen mouse \$0
  - ➤ Roll of duct tape: \$2.59
  - ➤ IEEE 488 adapter board: \$12
  - ➤ IEEE 488 cable: \$26



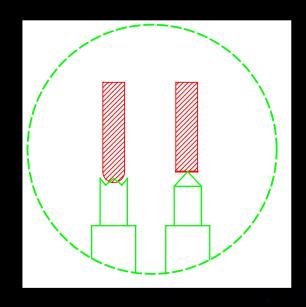
Bolt it all together...

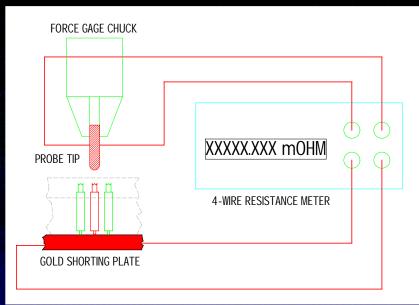




#### The Solution: Probe Considerations

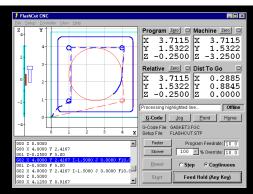
- Probe size should simulate DUT ball/pad geometry
- Wires must be soldered near tip to minimize bulk resistance
- Probe should be replaced often
- Nickel/Gold plating is recommended on tip
- Contactor must be firmly mounted to shorting plate
- Wires must be affixed to shorting plate on opposite ends to minimize bulk resistance





## The Solution (Software)

- Use existing NC G-Code software to drive robot
- Data Acquisition software: \$2100



yea-right.

- MS Excel macros/extensions Way too slow
- Visual Basic dumping into Excel OK (but a second PC was needed not enough system resources to run VB and NC controller on one machine- oh well...)





The birth of ECT AUTODATA





## The Solution - Features

- XYZ motion to .0002" precision
- Programmable in G-CODE or probe position imported from CAD data
- G-CODE triggered data gathering event with system feedback
- 1 gram force resolution
- 4-wire resistance to .01 milliohm resolution
- Data output into standard Excel spreadsheet
- Output formats: FReD curves, resistance maps, force maps, force and resistance histograms, monitored cycle testing, resistance/force statistics per contactor/lot, wear testing, etc.....

Total cost to integrate system: \$142.59

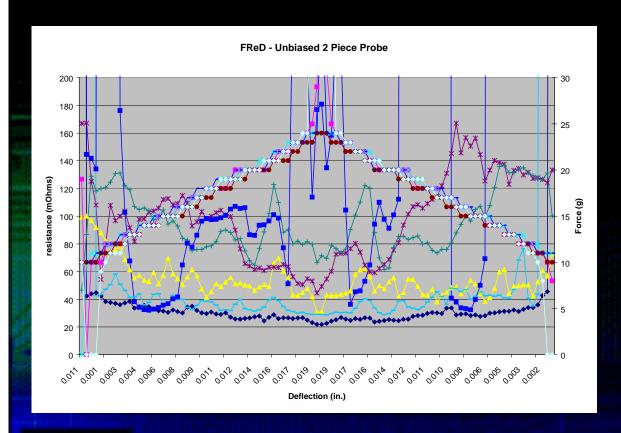
## Results - The Good, The Bad, The Ugly

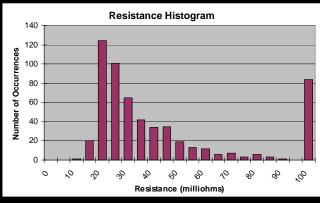
- Resistance maps show patterns of resistance failure
- FReD plots analyze a contact system's reliability over the entire actuation
- Resistance histograms and statistics (mean, standard deviation, skew, etc.) are good tools to evaluate improvements
- Force contours show mechanical failures

All of the tools above show inherent differences in contact technologies



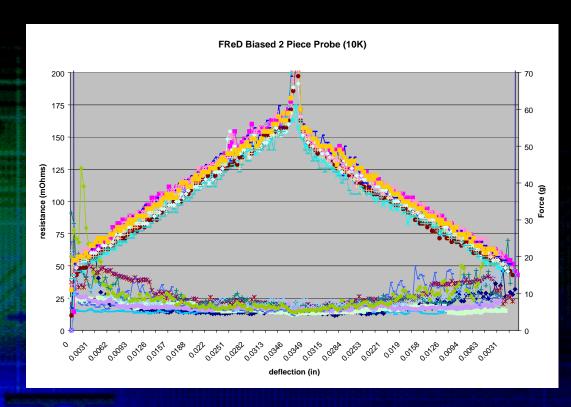
## Results: FReD Unbiased 2 Piece Probe

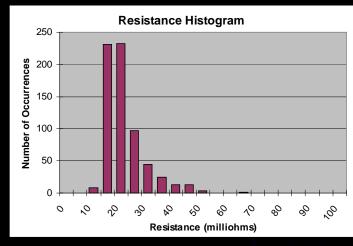




- Very smooth and predictable force
- Erratic and unreliable resistance - opens

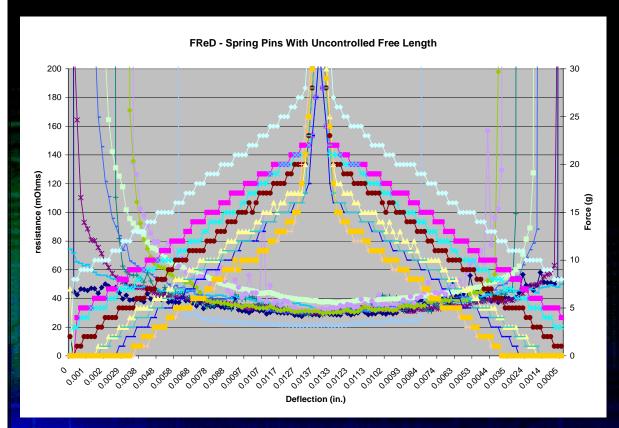
## Results: FReD Biased 2 Piece Spring Probe

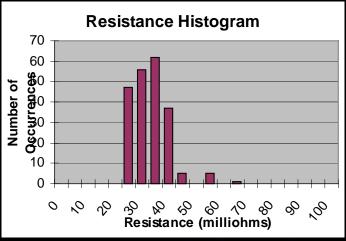




- ➤ Force in stroke can have 'grindy' feel
- Slight force differences for 'inward' and 'outward' stroke
- Very reliable and consistent resistance in working zone

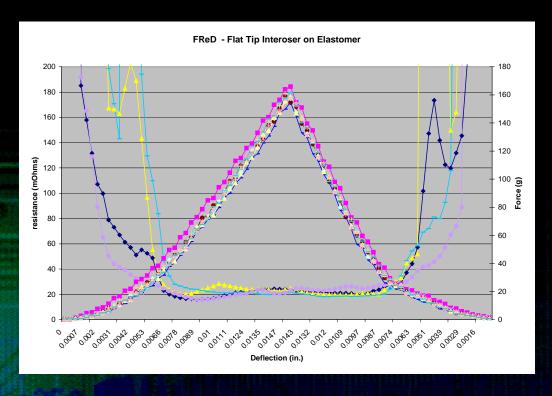
#### Results: FReD - Probe With Uncontrolled Free Length

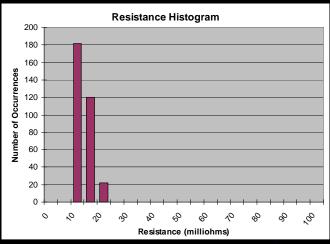




- Overlaid force traces have wide separation
- Wide variance in preload evident

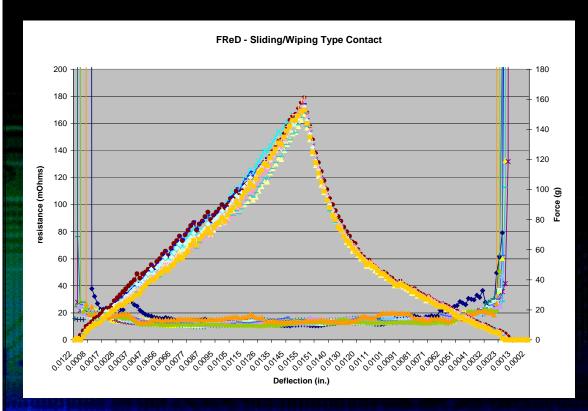
## Results: FReD - Elastomer/ Flat Interposer

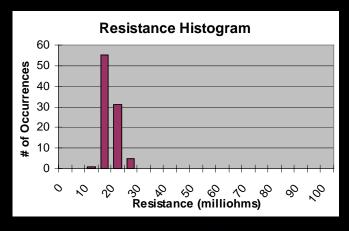




- ➤ High force system
- Resistance at beginning of stroke very unstable
- >Uniform force
- ➤ Uniform working resistance

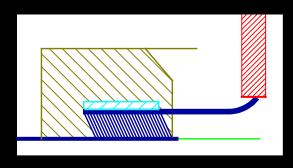
## Results: FReD - Sliding/Wiping Contact for QFP



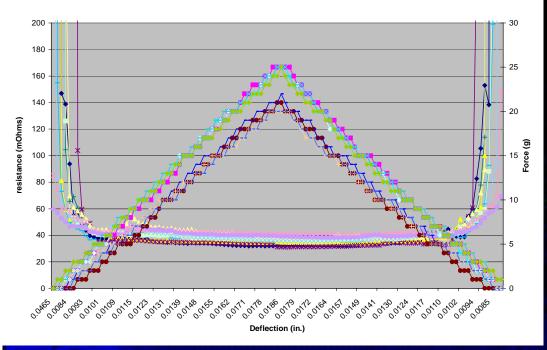


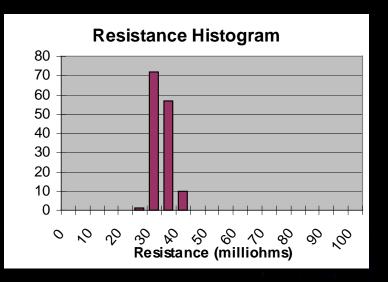
- Frictional 'stiction' effects during inward stroke can be seen in force curve
- Reliable and consistent resistance in working zone

## Results: FReD - ECT µHPC/PL



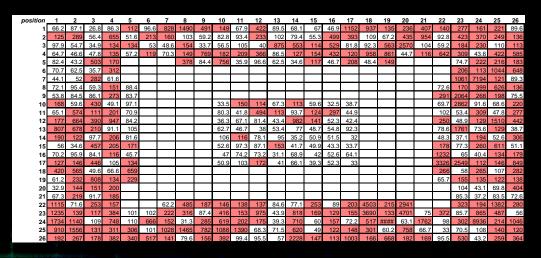


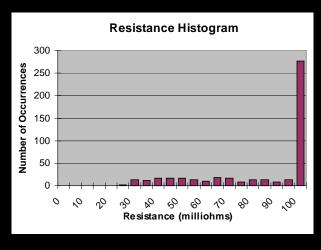


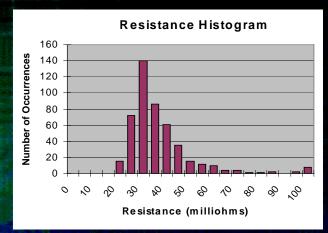


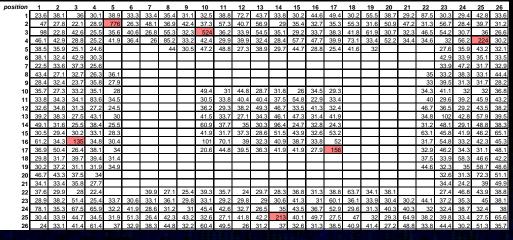
- Force in stroke very smooth
- Very reliable and consistent resistance in working zone

#### Results: Resistance Map Before and After Cleaning





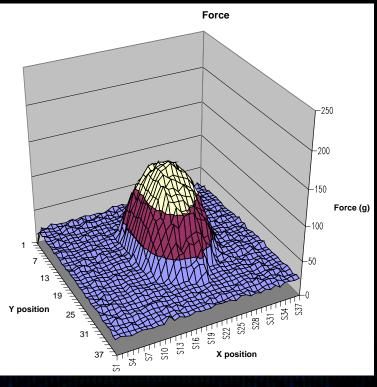




After standard maintenance cleaning process done, heavily used contactor nearly returns to usable condition

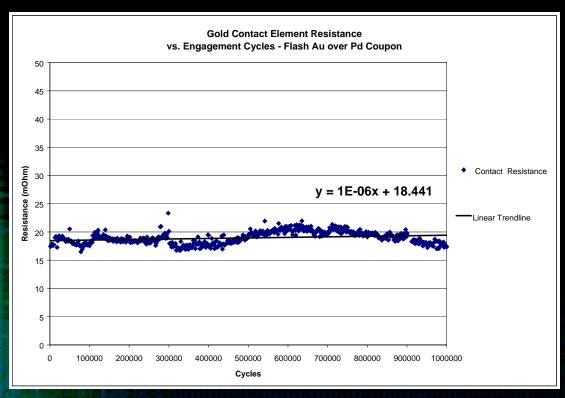
#### Results: Resistance/Force Map - Mechanical Failure



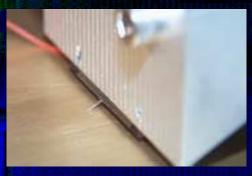


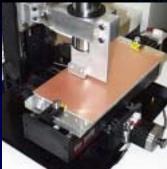
- Very large LGA contactor exhibited 'opens' in a large patch in the center
- Contactor guideplate suffered from extreme expansion due to hydroscopic effects. Center was 'domed', resulting in probe hitting contactor floor too early

#### Results: Wear Analysis - Au Contact Wear Against Pd-Au

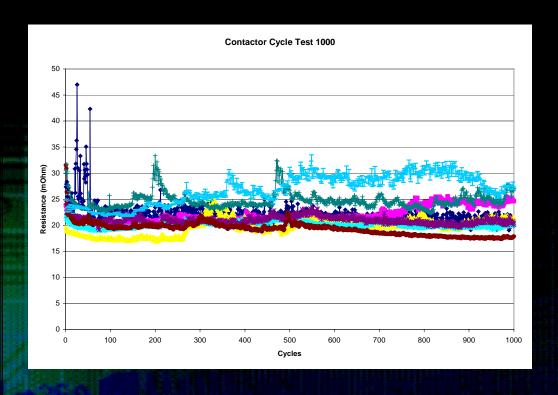


- ➤Robot was set up with µHPC/PL leadframe element
- Machine stroked element over Au flash over Pd coupon to simulate 1M actuations
- Resistance was recorded every 1K cycles





## Results: Monitored Cycle Testing



- Robot continuously cycled 25 pogo pin array until each pin was tested 1000 times
- Some early 'break-in' is seen



#### The Future of FReD

- FReD is always getting smarter
  - Working on improved software for simpler control and more powerful measurement
    - Faster data gathering
    - Automatic G-Code generation
    - Easier user interface
  - Resistance probe can easily be replaced with VNA or TDR for signal integrity verification of interfaces, POGO blocks, and contactors
  - New tests being proposed: spring pin pointing accuracy, spring pin bias reliability validation, BGA solder transfer investigation, Lead-free BGA contact study, .....



#### Conclusion

- FReD has proven to be an invaluable evaluation and characterization tool
- All contact systems have their own features and benefits - FReD is a tool to identify the pros and cons
- FReD is flexible and user friendly. Many different tests can be performed
- And of course.....
  - FReD is CHEAP.....

